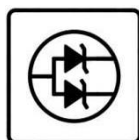


# MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED


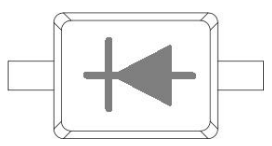
## **MMSZ5221B-MMSZ5259B**

**Product specification**

## FEATURES

- Planar Die Construction
- Ultra-Small Surface Mount Package
- General purpose, Medium Current
- Ideally Suited for Automated Assembly Processes

## Reference News

PACKAGE OUTLINE	PIN CONFIGURATION
	
SOD-123	

## Maximum Ratings(Ta=25 °C unless otherwise specified)

Characteristic	Symbol	Value	Unit
Forward Voltage (Note 2) @ I <sub>F</sub> = 10mA	V <sub>F</sub>	0.9	V
Power Dissipation(Note 1)	P <sub>d</sub>	500	mW
Thermal Resistance, Junction to Ambient Air	R <sub>θJA</sub>	357	°C/W
Operation Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150	°C

Notes:1. Device mounted on ceramic PCB; 7.6 mm x 9.4 mm x 0.87 mm with pad areas 25 mm<sup>2</sup>.

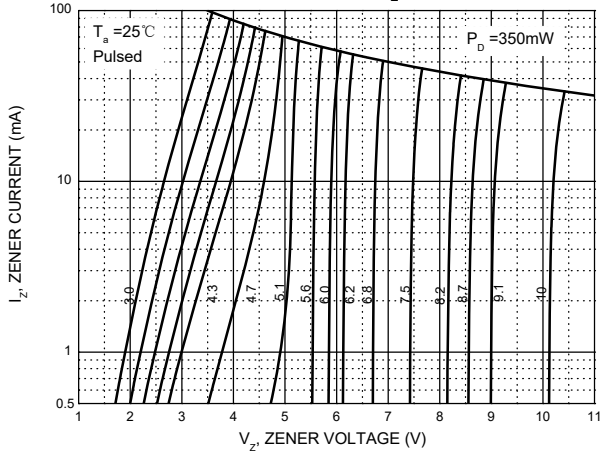
2. Tested with pulses, T<sub>p</sub> ≤ 1.0ms.

**ELECTRICAL CHARACTERISTICS**

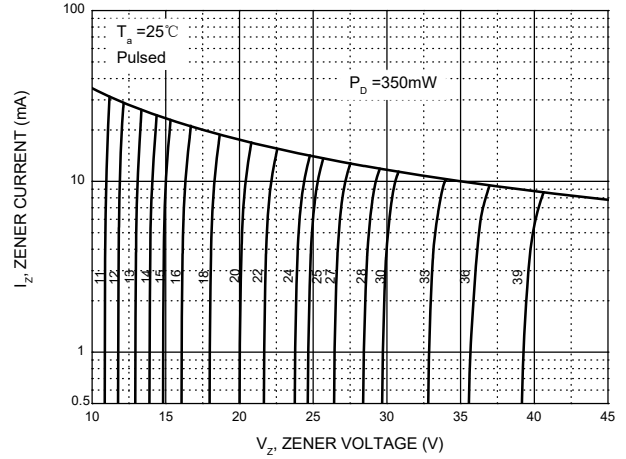
 T<sub>a</sub>=25°C unless otherwise specified

Type Number	Code	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 4)			Maximum Reverse Current	
		V <sub>Z</sub> @ I <sub>ZT</sub>			I <sub>ZT</sub>	Z <sub>ZT</sub> @ I <sub>ZT</sub>	Z <sub>ZK</sub> @ I <sub>ZK</sub>	I <sub>ZK</sub>	I <sub>R</sub>	V <sub>R</sub>
		Nom(V)	Min(V)	Max(V)	mA	Ω		mA	uA	V
MMSZ5221B	C1	2.4	2.28	2.52	20	30	1200	0.25	100	1.0
MMSZ5223B	C3	2.7	2.57	2.84	20	30	1300	0.25	75	1.0
MMSZ5225B	C5	3.0	2.85	3.15	20	30	1600	0.25	50	1.0
MMSZ5226B	G1	3.3	3.14	3.47	20	28	1600	0.25	25	1.0
MMSZ5227B	G2	3.6	3.42	3.78	20	24	1700	0.25	15	1.0
MMSZ5228B	G3	3.9	3.71	4.10	20	23	1900	0.25	10	1.0
MMSZ5229B	G4	4.3	4.09	4.52	20	22	2000	0.25	5	1.0
MMSZ5230B	G5	4.7	4.47	4.94	20	19	1900	0.25	5	2.0
MMSZ5231B	E1	5.1	4.85	5.36	20	17	1600	0.25	5	2.0
MMSZ5232B	E2	5.6	5.32	5.88	20	11	1600	0.25	5	3.0
MMSZ5233B	E3	6.0	5.70	6.30	20	7	1600	0.25	5	3.5
MMSZ5234B	E4	6.2	5.89	6.51	20	7	1000	0.25	5	4.0
MMSZ5235B	E5	6.8	6.46	7.14	20	5	750	0.25	3	5.0
MMSZ5236B	F1	7.5	7.13	7.88	20	6	500	0.25	3	6.0
MMSZ5237B	F2	8.2	7.79	8.61	20	8	500	0.25	3	6.5
MMSZ5238B	F3	8.7	8.27	9.14	20	8	600	0.25	3	6.5
MMSZ5239B	F4	9.1	8.65	9.56	20	10	600	0.25	3	7.0
MMSZ5240B	F5	10	9.50	10.50	20	17	600	0.25	3	8.0
MMSZ5241B	H1	11	10.45	11.55	20	22	600	0.25	2.0	8.4
MMSZ5242B	H2	12	11.40	12.60	20	30	600	0.25	1.0	9.1
MMSZ5243B	H3	13	12.35	13.65	9.5	13	600	0.25	0.5	9.9
MMSZ5244B	H4	14	13.30	14.70	9.0	15	600	0.25	0.1	10
MMSZ5245B	H5	15	14.25	15.75	8.5	16	600	0.25	0.1	11
MMSZ5246B	J1	16	15.20	16.80	7.8	17	600	0.25	0.1	12
MMSZ5248B	J3	18	17.10	18.90	7.0	21	600	0.25	0.1	14
MMSZ5250B	J5	20	19.00	21.00	6.2	25	600	0.25	0.1	15
MMSZ5251B	K1	22	20.90	23.10	5.6	29	600	0.25	0.1	17
MMSZ5252B	K2	24	22.80	25.20	5.2	33	600	0.25	0.1	18
MMSZ5253B	K3	25	23.75	26.25	5.0	35	600	0.25	0.1	19
MMSZ5254B	K4	27	25.65	28.35	5.0	41	600	0.25	0.1	21
MMSZ5255B	K5	28	26.60	29.40	4.5	44	600	0.25	0.1	21
MMSZ5256B	M1	30	28.50	31.50	4.2	49	600	0.25	0.1	23
MMSZ5257B	M2	33	31.35	34.65	3.8	58	700	0.25	0.1	25
MMSZ5258B	M3	36	34.20	37.80	3.4	70	700	0.25	0.1	27
MMSZ5259B	M4	39	37.05	40.95	3.2	80	800	0.25	0.1	30
MMSZ5266B	P1	68	64.6	71.4	1.8	230	1600	0.25	0.1	52

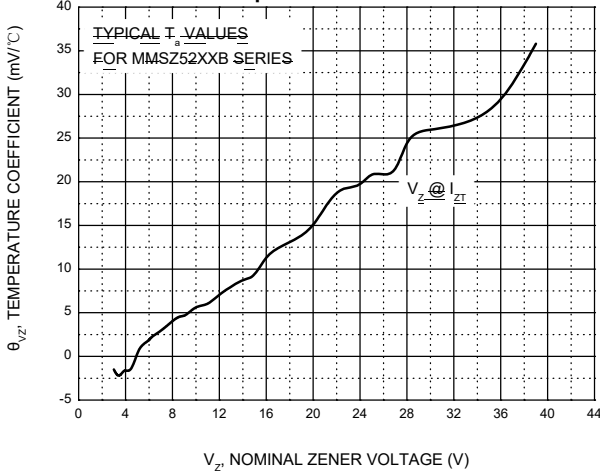
Zener Characteristics ( $V_z$  Up to 10 V)



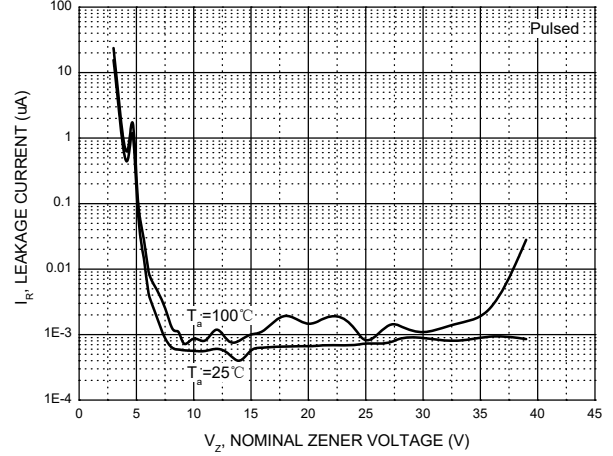
Zener Characteristics (11 V to 39 V)



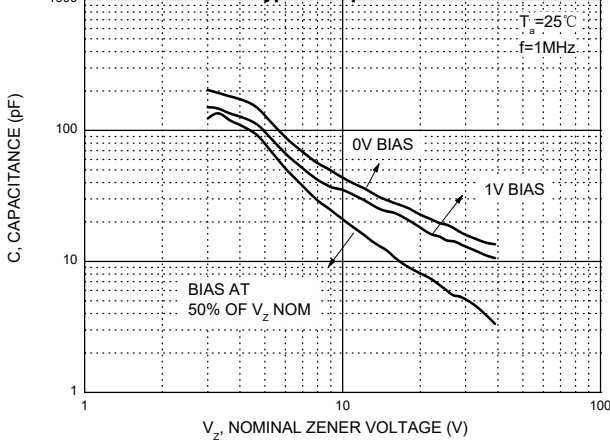
Temperature Coefficients



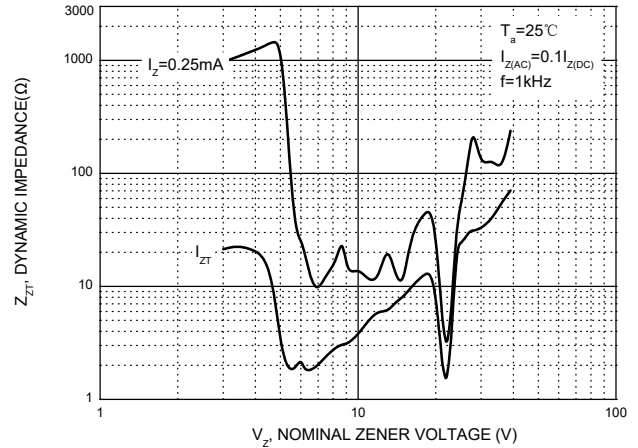
Typical Leakage Current



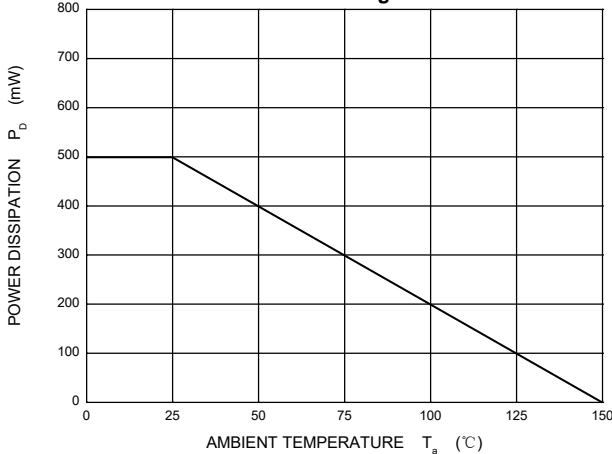
Typical Capacitance



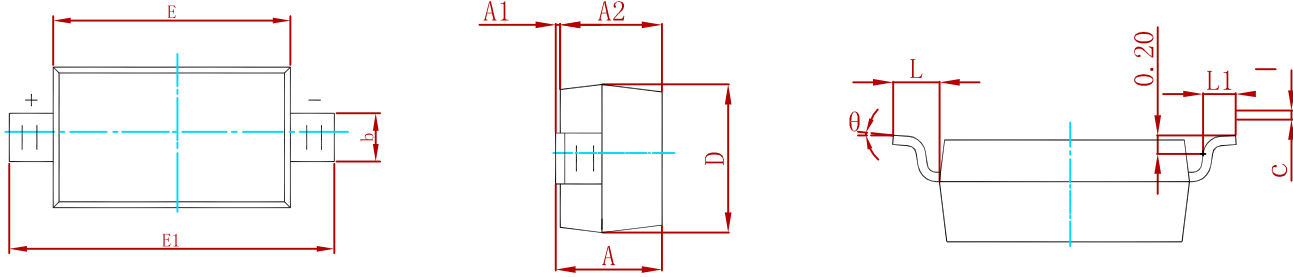
Effect of Zener Voltage on Zener Impedance



Power Derating Curve

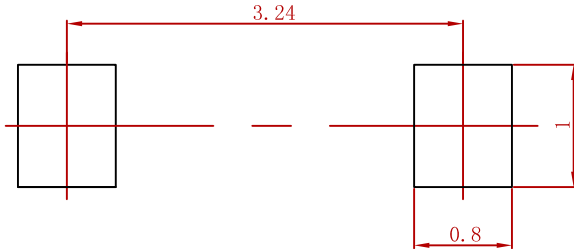


**PACKAGE MECHANICAL DATA**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.450	0.650	0.018	0.026
c	0.080	0.150	0.003	0.006
D	1.500	1.700	0.059	0.067
E	2.600	2.800	0.102	0.110
E1	3.550	3.850	0.140	0.152
L	0.500 REF		0.020 REF	
L1	0.250	0.450	0.010	0.018
θ	0°	8°	0°	8°

**Suggested Pad Layout**



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance:  $\pm 0.05\text{mm}$ .
  3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
MMSZ5221B-MMSZ5259B	SOD-123	3000

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